2SK3600-01L,S,SJ

200304

FUJI POWER MOSFET
Super FAP-G Series

N-CHANNEL SILICON POWER MOSFET

■ Features

- High speed switching
- Low on-resistance
- No secondary breadown
- Low driving power
- Avalanche-proof

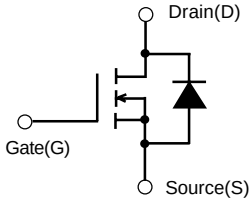
■ Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

■ Outline Drawings (mm)

P4

■ Equivalent circuit schematic



■ Maximum ratings and characteristic Absolute maximum ratings

● (Tc=25°C unless otherwise specified)

Item	Symbol		Ratings	Unit
Drain-source voltage	V_{DS}		100	V
	V_{DSX} *5		70	V
Continuous drain current	I_D		±29	A
Pulsed drain current	$I_{D(puls)}$		±116	A
Gate-source voltage	V_{GS}		±30	V
Non-repetitive Avalanche current	I_{AS} *2		29	A
Maximum Avalanche Energy	E_{AS} *1		155.8	mJ
Maximum Drain-Source dV/dt	dV_{DS}/dt *4		20	kV/µs
Peak Diode Recovery dV/dt	dV/dt *3		5	kV/µs
Max. power dissipation	P_D	Ta=25°C	1.67	W
		Tc=25°C	105	
Operating and storage temperature range	T_{ch}		+150	°C
	T_{stg}		-55 to +150	°C

*1 L=222µH, Vcc=48V, Tch=25°C, See to Avalanche Energy Graph *2 Tch ≦150°C
*3 I_F≦ -I_D, -di/dt=50A/µs, Vcc≦ BV_{DSS}, Tch≦ 150°C *4 V_{DS} ≦ 100V *5 V_{GS}=-30V

● Electrical characteristics (T_C =25°C unless otherwise specified)

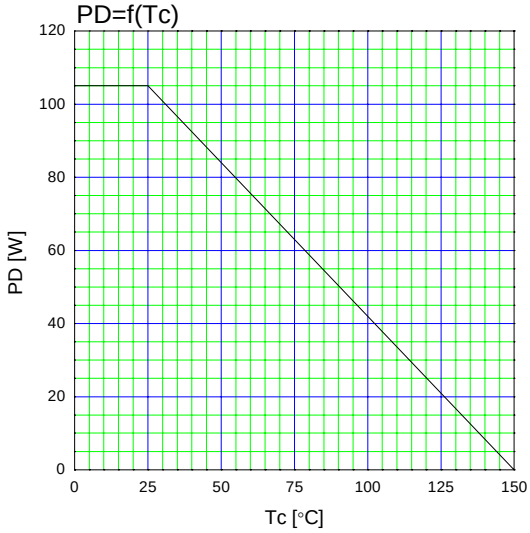
Item	Symbol	Test Conditions		Min.	Typ.	Max.	Units
Drain-source breakdown voltaget	$V_{(BR)DSS}$	I_D= 250µA V_{GS}=0V		100			V
Gate threshold voltage	$V_{GS(th)}$	I_D= 250µA V_{DS}=V_{GS}		3.0		5.0	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=100V V_{GS}=0V	Tch=25°C			25	µA
		V_{DS}=80V V_{GS}=0V	Tch=125°C			250	
Gate-source leakage current	I_{GSS}	V_{GS}=±30V V_{DS}=0V			10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	I_D=10A V_{GS}=10V			47	62	mΩ
Forward transcondutance	gfs	I_D=10A V_{DS}=25V		6	12		S
Input capacitance	Ciss	V_{DS}=75V			730	1095	pF
Output capacitance	Coss	V_{GS}=0V			190	285	
Reverse transfer capacitance	Crss	f=1MHz			12	18	
Turn-on time ton	td(on)	Vcc=48V I_D=10A			12	18	ns
	tr	V_{GS}=10V			3.8	6	
Turn-off time toff	td(off)	R_{GS}=10 Ω			23	35	
	tf				8.5	13	
Total Gate Charge	Q_G	Vcc=50V			22	33	nC
Gate-Source Charge	Q_{GS}	I_D=20A			9	13.5	
Gate-Drain Charge	Q_{GD}	V_{GS}=10V			6	9	
Avalanche capability	I_{AV}	L=222µH Tch=25°C		29			A
Diode forward on-voltage	V_{SD}	I_F=20A V_{GS}=0V Tch=25°C			1.10	1.65	V
Reverse recovery time	trr	I_F=20A V_{GS}=0V			65		ns
Reverse recovery charge	Qrr	-di/dt=100A/µs Tch=25°C			0.17		µC

● Thermalcharacteristics

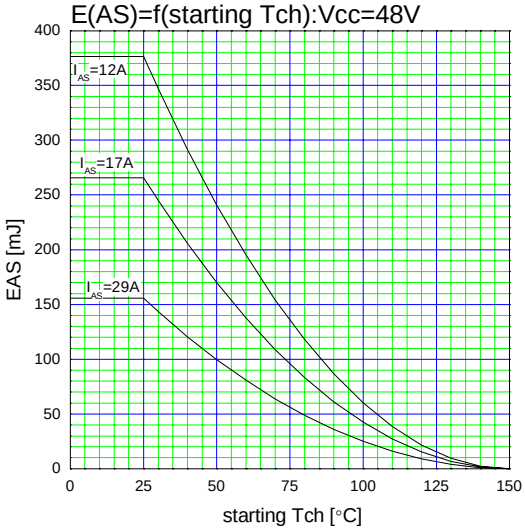
Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	$R_{th(ch-c)}$	channel to case			1.191	°C/W
	$R_{th(ch-a)}$	channel to ambient			75.0	°C/W

Characteristics

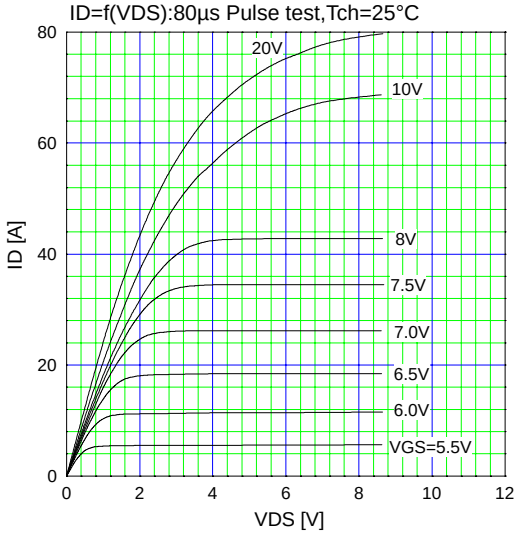
Allowable Power Dissipation
PD=f(Tc)



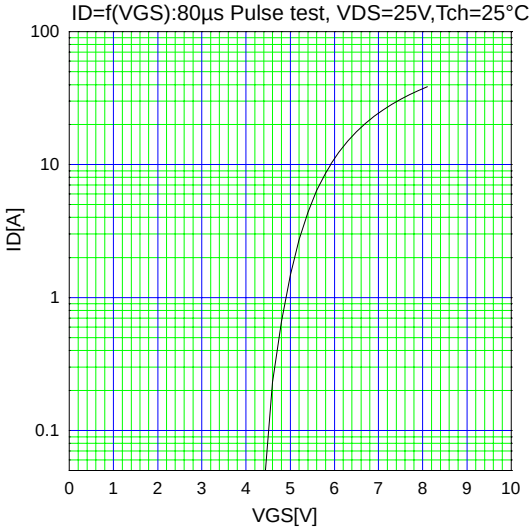
Maximum Avalanche Energy vs. starting Tch
E(AS)=f(starting Tch):Vcc=48V



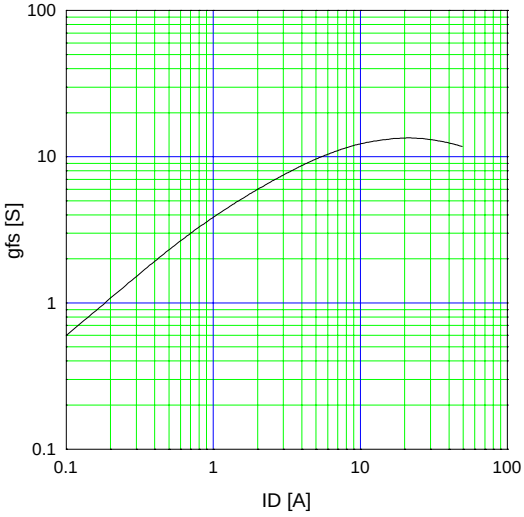
Typical Output Characteristics
ID=f(VDS):80µs Pulse test,Tch=25°C



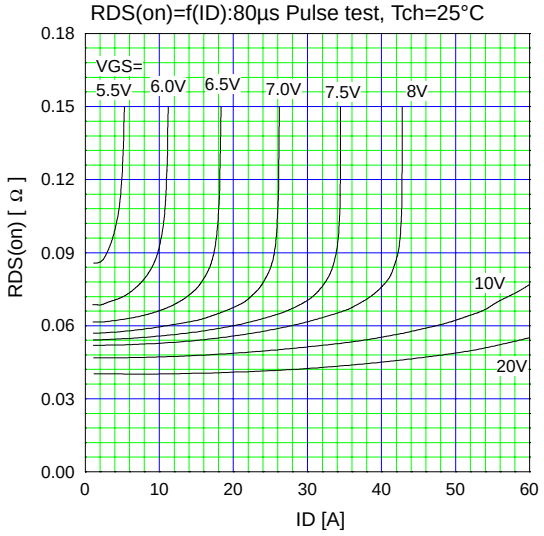
Typical Transfer Characteristic
ID=f(VGS):80µs Pulse test, VDS=25V,Tch=25°C



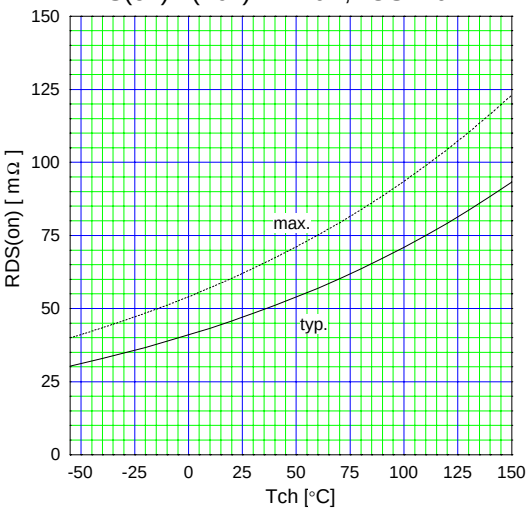
Typical Transconductance
gfs=f(ID):80µs Pulse test, VDS=25V,Tch=25°C



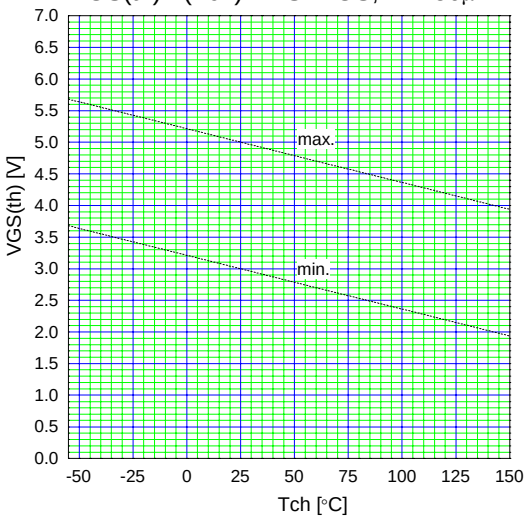
Typical Drain-Source on-state Resistance
RDS(on)=f(ID):80µs Pulse test, Tch=25°C



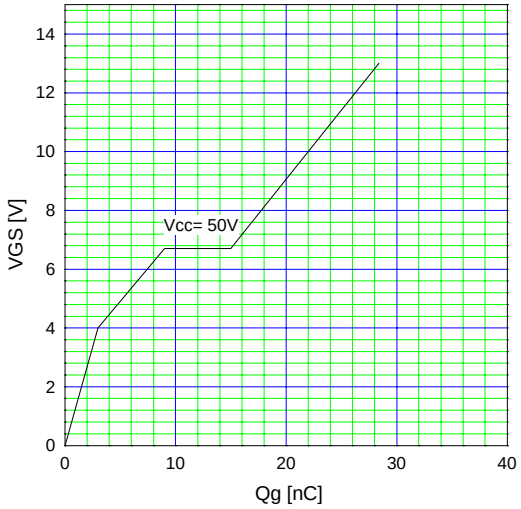
Drain-Source On-state Resistance
RDS(on)=f(Tch):ID=10A,VGS=10V



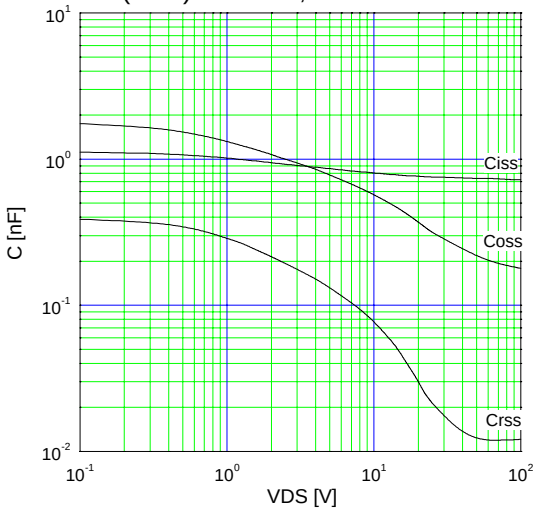
Gate Threshold Voltage vs. Tch
VGS(th)=f(Tch):VDS=VGS,ID=250μA



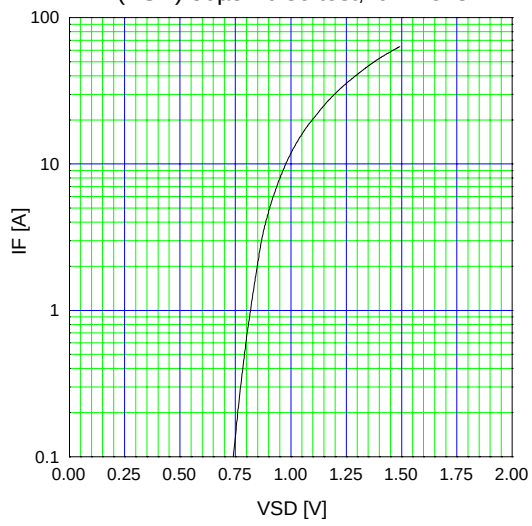
Typical Gate Charge Characteristics
VGS=f(Qg):ID=20A, Tch=25°C



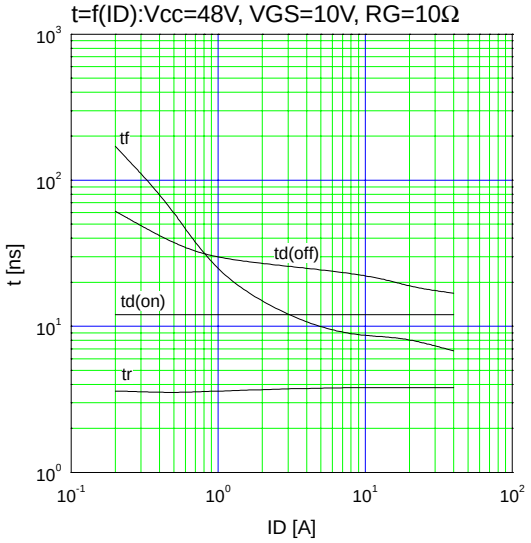
Typical Capacitance
C=f(VDS):VGS=0V,f=1MHz



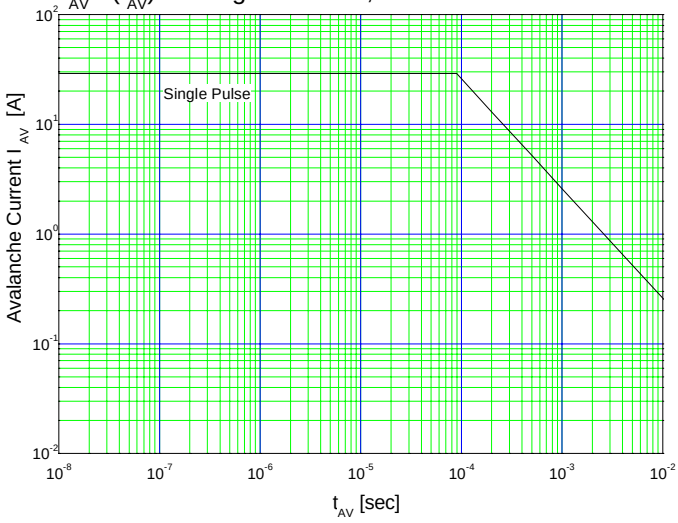
Typical Forward Characteristics of Reverse Diode
IF=f(VSD):80μs Pulse test,Tch=25°C



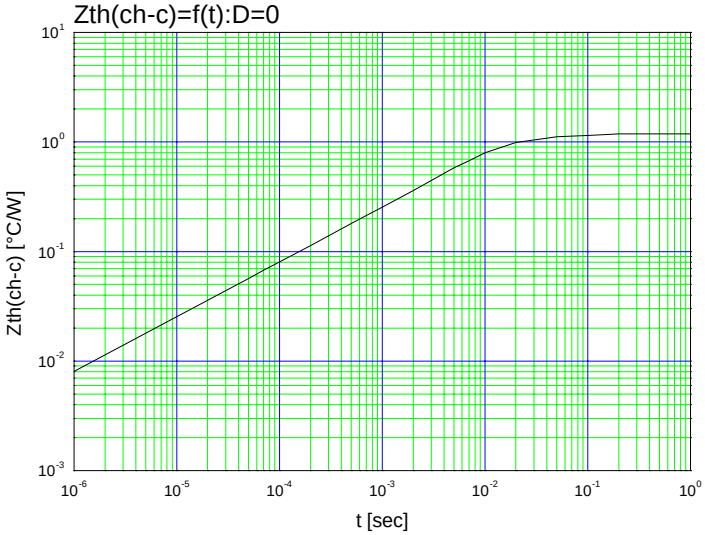
Typical Switching Characteristics vs. ID
t=f(ID):Vcc=48V, VGS=10V, RG=10Ω



Maximum Avalanche Current Pulsewidth
I_{AV}=f(t_{AV}):starting Tch=25°C,Vcc=48V

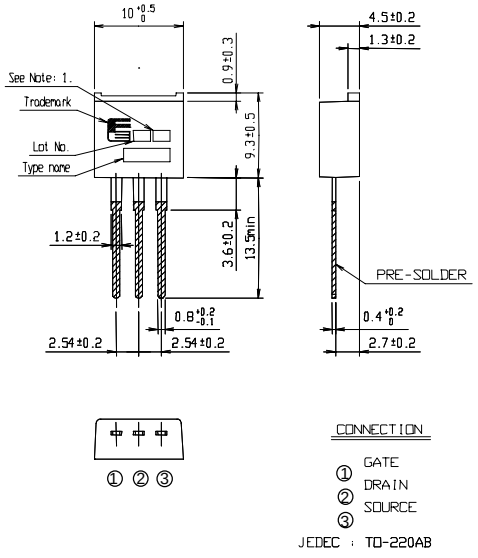


Maximum Transient Thermal Impedance
Zth(ch-c)=f(t):D=0

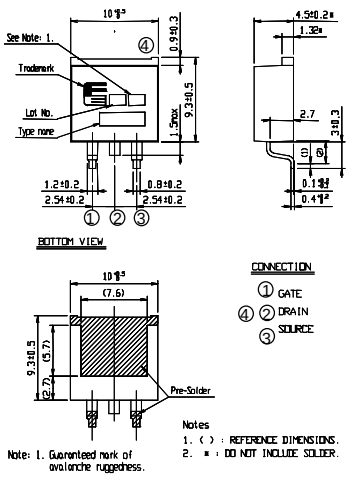


■ Outline Drawings (mm)

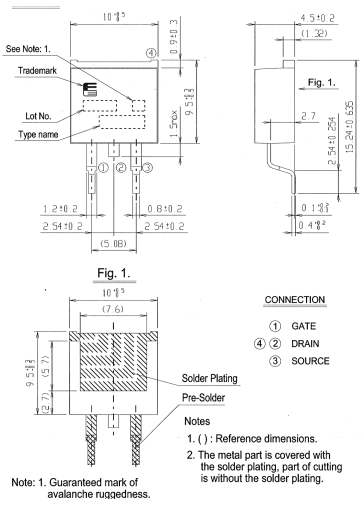
Type(L)



Type(S)



Type(SJ)



http://www.fujielectric.co.jp/denshi/scd/